

1ST Announcement

14th International Congress on Thermal Stresses (ICTS 2025)

Hong Kong SAR, P.R. CHINA (2-6 June 2025)

Following the success of previous conferences in Hamamatsu, Japan (1995); Rochester, USA (1997); Cracow, Poland (1999); Osaka, Japan (2001); Blacksburg, USA (2003); Vienna, Austria (2005); Taipei, Taiwan (2007); Urbana Champaign, Illinois, USA (2009); Budapest, Hungary (2011); Nanjing, P.R. China (2013); Salerno, Italy (2016); Hangzhou, P.R. China (2019); Luleå, Sweden, (2023), we, a group of enthusiastic academic researchers and professionals in mechanics in Hong Kong SAR, are proposing to bring this great event for the first time to Hong Kong SAR. Here we propose to host ICTS on **June 2nd-6th of 2025 in Hong Kong SAR, P.R. China.**

The objective of the congress is to provide a forum for scientists and engineers from academia, research laboratories, and industry from all over the world that are involved in the field of thermal stresses. It is hoped that this meeting place will stimulate exchange of ideas and stimulate cooperation between participants. It will thereby promote development and research in areas related to Thermal Stresses.

The target number of expected participants for ICTS 2025 is 100-220, including 50-100 regular participants, 50-100 student participation (including paper and poster presentations), and about 20 non-presenting participants from government and industries. The event is a three-day technical program, which tentatively includes approximately 4 plenary lectures, 4 semi-plenary lectures, 50 invited lectures, 80-100 regular presentations, 20 local non-presenting participants (mostly local engineers and professionals who are sponsored by their employers for continuing self-development purposes), and 20-50 poster presentations. We have successfully hosted many international and regional conferences, and we believe that Hong Kong SAR, P.R. China is the best choice for hosting the ICTS-2025.

ICTS is affiliated with the *International Union of Theoretical Mechanics* (IUTAM). The congress is held in cooperation with the *Journal of Thermal Stresses* (JTS). We are grateful for our affiliates including *The Hong Kong Institution of Engineers* (HKIE) (to be confirmed), and *Institute of Mechanical Engineers Hong Kong Branch* (IMechE Hong Kong) (to be confirmed) who are leading organizations for professional engineers in Hong Kong. **Department of Architecture and Civil Engineering at City University of Hong Kong** and **ASME Hong Kong Section** will host the congress. We are also seeking sponsorships from the local government departments, higher institutions and other relevant industries for support and sponsorship.

We welcome all of you to Hong Kong SAR and hope you enjoy the conference as well as the social events.

Topics for Submission:

This is a conference on thermal stresses and related topics, with particular focus on the following, but not limited to them:

- Thermal Stresses and Deformations
- Thermoelasticity and Viscoelasticity
- Thermal Stresses in
 - Contact Mechanics
 - Dynamic Problems
 - Fracture and Fatigue of Heterogeneous Materials and Manufacturing
- Thermo-Hygro-Mechanics
- Thermo-Biomechanics
- Thermal Shock
- Continuum Thermomechanics
- Heat Conduction, Convection and Radiation Problems
- Experimental Methods in Thermomechanics
- Computational Methods in Thermomechanics
- Control of Thermal Structures
- Instability and Localization under Thermomechanic Loading
- Inverse and Optimization Methods in Thermomechanics
- Thermal-Induced Fracture of Smart Materials
- Thermal Stresses in Smart Materials

Organizer:

- The Department of Architecture and Civil Engineering, City University of Hong Kong
- The American Society of Mechanical Engineers (Hong Kong Section)

Co-organizers:

TBD

- International Union of Theoretical Mechanics (IUTAM)
- Journal of Thermal Stresses (JTS)
- Hong Kong Institution of Engineers (HKIE)
- Institute of Mechanical Engineers Hong Kong Branch (IMEchE Hong Kong)
- Department of Architecture and Civil Engineering, City University of Hong Kong
- American Society of Mechanical Engineers (Hong Kong Section)

Congress Chair:

C.W. Lim, City University of Hong Kong.

Congress Co-Chairs:

- **Weiqiu Chen**, Zhejiang University, PR China
- **Lars-Erik Lindgren**, Luleå University of Technology
- **Martin Ostoja-Starzewski**, University of Illinois at Urbana-Champaign, USA

Local Organizing Committee Members:

C.W. Lim, Wisal Ahmed, Guifeng Wang, Chen Liang, Cong Wang, Yanhong Guan, Yifeng Ai, Tian Wang

Scientific Committee:

- **Moncef Aouadi**, University of Carthage, Tunisia
- **Jan Awrejcewicz**, Lodz University of Technology, Poland
- **J.R. Barber**, University of Michigan, USA
- **Romesh C. Batra**, Virginia Polytechnic Institute & State University, USA
- **Erasmus Carrera**, Politecnico of Turin, Italy
- **Ching-kong Chao**, National Taiwan University of Science and Technology, Taiwan
- **Stan Chirita**, University of Iasi, Romania
- **Michele Ciarletta**, University of Salerno, Italy
- **Simona De Cicco**, University of Naples Federico II, Italy
- **M.Reza Eslami**, Amirkabir University of Technology, Iran
- **José Ramón Fernández**, University of Vigo, Spain
- **Cun Fa Gao**, Nanjing University of Aeronautics and Astronautics, China
- **Katarzyna Górska**, Institute of Nuclear Physics, PAS, Poland
- **Jesper Hattel**, Technical University of Denmark, Denmark
- **Dorin Iesan**, University of Iasi, Romania
- **Masayuki Ishihara**, Osaka Metropolitan University, Japan
- **Santosh Kapuria**, Indian Institute of Technology Delhi, India
- **Ryuusuke Kawamura**, Indian Institute of Technology, New Delhi, India
- **Shirong Li**, Yangzhou University, Jiangsu, China
Pier Marzocca, RMIT University, Australia
- **Takuya Morimoto**, Shimane University, Japan
- **Zenon Mróz**, Polish Academy of Sciences, Poland
- **Santwana Mukhopadhyay**, Indian Institute of Technology (BHU), India
- **Naotake Noda**, Shizuoka University, Japan
- **Francesca Passarella**, University of Salerno, Italy
- **Yuriy Povstenko**, Jan Dlugosz University of Czestochowa, Poland
- **Ramón Quintanilla de Latorre**, Polytechnical University of Catalonia, Spain
- **Sei-Ichiro Sakata**, Kindai University, Japan
- **Antonio Sellitto**, University of Salerno, Italy
- **Merab Svanadze**, Ilia State University, Georgia

- Jan Taler, Cracow University of Technology, Poland
- Kumar K. Tamma, University of Minnesota, USA
- Vincenzo Tibullo, University of Salerno, Italy
- Andrzej Tylikowski, Warsaw University of Technology, Poland
- Xinwei Wang, Iowa State University, USA
- Fan Yang, Tongji University, China

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Important Key Dates:

Abstract submission: 28th February 2025

Early-bird registration: 31st March 2025

Regular registration: 30th April 2025

On-site registration: on site

Submit an abstract of approximately 200 words on the congress website. Please include the following information: the scope of the paper, the author's affiliation, correspondence address, postal code, email address, funding information, and other relevant details. Please submit the abstract using the provided template.

Registration Fee:

Please find details on the congress website, <https://www.icts2025.org/>.